PS9822-1,-2

1 Mbps OPEN COLLECTOR OUTPUT TYPE
8-PIN SSOP (SO-8) HIGH-SPEED PHOTOCOUPLER

R08DS0262EJ0200
Rev.2.00
May 20, 2026

DESCRIPTION

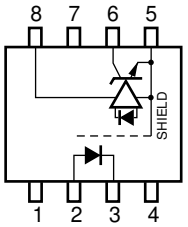
The PS9822-1 and PS9822-2 are active-low type high-speed photocouplers that use an AlGaAs light-emitting diode on the input side and a photodetector IC that includes a photodiode and a signal processor on the same chip on the output side.
The PS9822-1, -2 are high-speed digital output type photocouplers designed specifically for low circuit current. The PS9822-2 is suitable for high density applications.

FEATURES

- Supply Voltage
  N rank: V_{CC} = 3.3 V
  L rank: V_{CC} = 5 V
- Pulse width distortion ($|t_{PHL}-t_{PLH}|$ = 200 ns MAX.)
- 40% reduction of mounting area (5-pin SOP × 2)
- High-speed (1 Mbps)
- High isolation voltage (BV = 2 500 Vr.m.s.)
- Open collector output
- Ordering number of tape product: PS9822-1-F3 : 1 500 pcs/reel
- : PS9822-2-F3 : 1 500 pcs/reel
- Pb-Free product
- Safety standards
  - UL : UL 1577, Single protection
  - VDE : DIN EN IEC 60747-5-5 (Option)

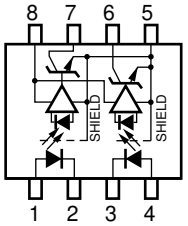
PIN CONNECTION
(Top View)

PS9822-1



1. NC
2. Anode
3. Cathode
4. NC
5. GND
6. V_O
7. NC
8. V_{CC}

PS9822-2



1. Anode1
2. Cathode1
3. Cathode2
4. Anode2
5. GND
6. V_{O2}
7. V_{O1}
8. V_{CC}

APPLICATIONS

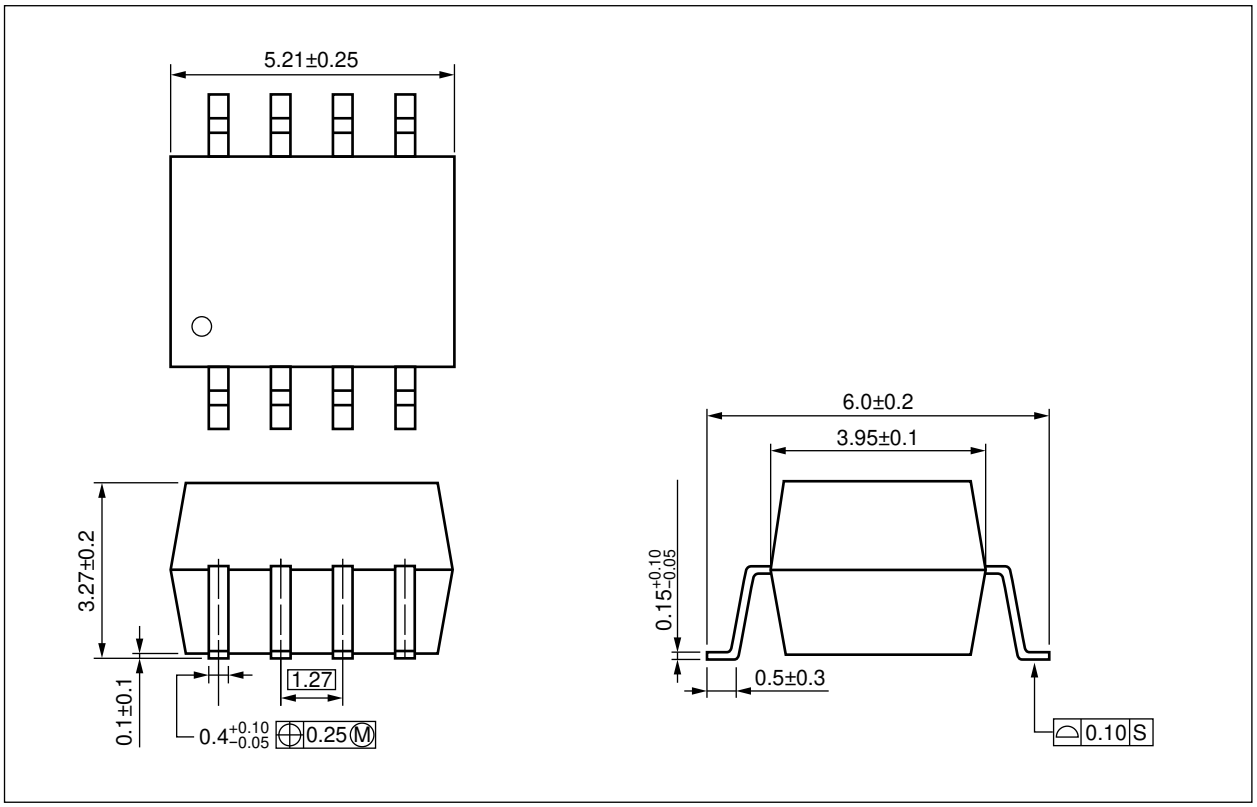
- PoE (Power over Ethernet)
- Measurement equipment
- FA Network

TRUTH TABLE

LED	Output
ON	L
OFF	H

Start of mass production
Oct.2008

PACKAGE DIMENSIONS (UNIT: mm)



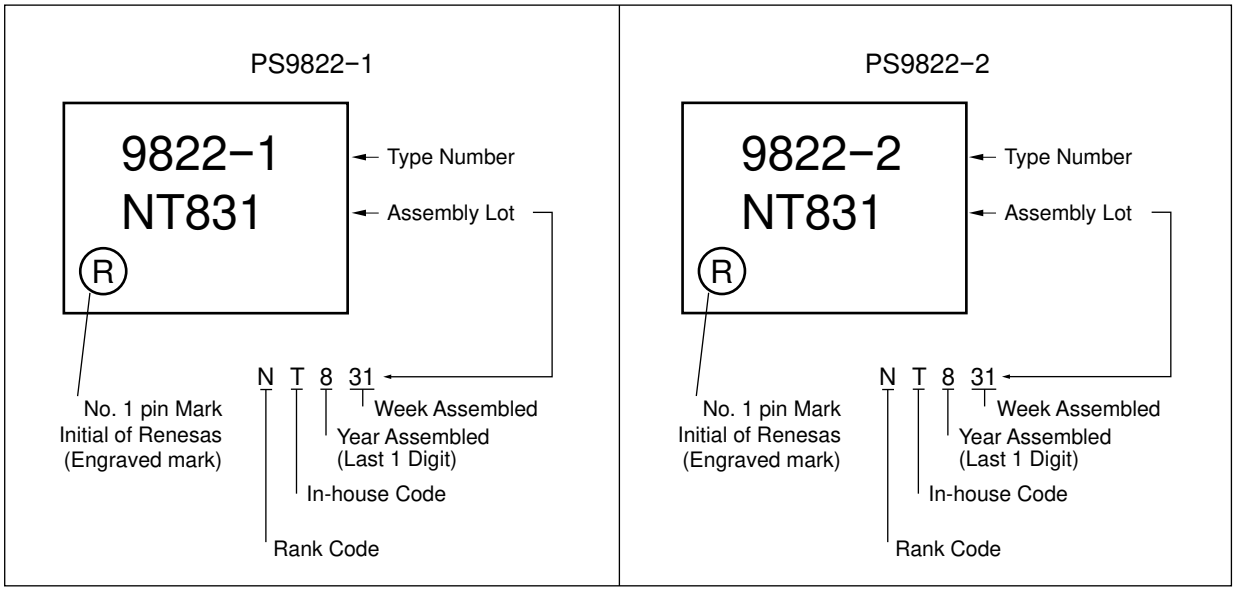
Weight: 0.14g (TYP.)

PHOTOCOUPLER CONSTRUCTION

Parameter	MIN.
Air Distance	4 mm
Creepage Distance	4 mm
Isolation Distance	0.2 mm

MARKING EXAMPLE

Ni/Pd/Au PLATING



ORDERING INFORMATION

Part Number	Order Number[*4]	Rank	Solder Plating Specification	Packing Style	Safety Standards Approval	Application Part Number [*1]
PS9822-1	PS9822-1-AX	N[*2]	Pb-Free (Ni/Pd/Au)	20 pcs (Tape 20 pcs cut)	Standard products (UL, Approved)	PS9822-1
		L[*3]				
PS9822-1-F3	PS9822-1-F3-AX	N[*2]		Embossed Tape 1 500 pcs/reel		
		L[*3]				
PS9822-2	PS9822-2-AX	N[*2]		20 pcs (Tape 20 pcs cut)		PS9822-2
		L[*3]				
PS9822-2-F3	PS9822-2-F3-AX	N[*2]		Embossed Tape 1 500 pcs/reel		
		L[*3]				
PS9822-1-V	PS9822-1-V-AX	N[*2]		20 pcs (Tape 20 pcs cut)	UL, VDE Approved	PS9822-1
		L[*3]				
PS9822-1-V-F3	PS9822-1-V-F3-AX	N[*2]		Embossed Tape 1 500 pcs/reel		
		L[*3]				
PS9822-2-V	PS9822-2-V-AX	N[*2]		20 pcs (Tape 20 pcs cut)		PS9822-2
		L[*3]				
PS9822-2-V-F3	PS9822-2-V-F3-AX	N[*2]		Embossed Tape 1 500 pcs/reel		
		L[*3]				

Notes*: 1. For the application of the Safety Standard, following part number should be used.
2. N rank: VCC = 3.3 V
3. L rank: VCC = 5 V
4. When specifying rank, please add “-rank” after Order Number.
ex. N rank : PS9822-1-AX-N

ABSOLUTE MAXIMUM RATINGS (T_A = 25 °C, unless otherwise specified)

Parameter		Symbol	Ratings		Unit
			PS9822-1	PS9822-2	
Diode	Forward Current	I_F	20 *1	15 *2	mA
	Reverse Voltage	V_R	5		V/ch
Detector	Supply Voltage	V_{CC}	7		V
	Output Voltage	V_O	7		V/ch
	Output Current	I_O	20		mA/ch
	Power Dissipation *3	P_C	40		mW/ch
Isolation Voltage *4		BV	2 500		Vr.m.s.
Operating Ambient Temperature		T_A	− 40 to + 100		°C
Storage Temperature		T_{stg}	− 55 to + 125		°C

Notes*: 1. Reduced to 0.38 mA/°C at T_A = 80 °C or more.
2. Reduced to 0.13 mA/°C at T_A = 80 °C or more.
3. Applies to output pin V_O (collector pin). Reduced to 1.5 mW/°C at T_A = 80 °C or more.
4. AC voltage for 1 minute at T_A = 25 °C, RH = 60 % between input and output.
Pins 1-4 shorted together, 5-8 shorted together.

RECOMMENDED OPERATING CONDITIONS

Parameter		Symbol	MIN.	TYP.	MAX.	Unit
Low Level Input Voltage		V_{FL}	0		0.8	V
High Level Input Current		I_{FH}	6.3	10	12.5	mA
Supply Voltage	N rank	V_{CC}	2.7	3.3	3.6	V
	L rank		4.5	5.0	5.5	
Pull-up Resistance		R_L	330		4 k	Ω
TLL (R_L = 1.0 kΩ, loads)		N			3	

ELECTRICAL CHARACTERISTICS : N rank (T_A = –40 to +100 °C, unless otherwise specified)

Parameter		Symbol	Conditions	MIN.	TYP.*1	MAX.	Unit
Diode	Forward Voltage	V_F	I_F = 10 mA, T_A = 25 °C		1.6	1.8	V
	Reverse Current	I_R	V_R = 3 V, T_A = 25 °C			10	μA
	Terminal Capacitance	C_t	V = 0 V, f = 1 MHz, T_A = 25 °C		30		pF
Detector	High Level Output Current	I_{OH}	V_{CC} = V_O = 3.3 V, V_F = 0.8 V		1	100	μA
	Low Level Output Voltage*2	V_{OL}	V_{CC} = 3.3 V, I_F = 5 mA, I_{OL} = 10 mA		0.2	0.6	V
	High Level Supply Current (PS9822-1)	I_{CCH}	V_{CC} = 3.3 V, I_F = 0 mA, V_O = Open			2	mA
	High Level Supply Current (PS9822-2)					4	
	Low Level Supply Current (PS9822-1)	I_{CCL}	V_{CC} = 3.3 V, I_F = 10 mA, V_O = Open			3	
	Low Level Supply Current (PS9822-2)					6	
Coupled	Threshold Input Current (H → L)	I_{FHL}	V_{CC} = 3.3 V, V_O = 0.8 V, R_L = 350 Ω		2	5	mA
	Isolation Resistance	R_{I-O}	V_{I-O} = 1 kV_{DC}, RH = 40 to 60 %, T_A = 25 °C	10^{11}			Ω
	Isolation Capacitance	C_{I-O}	V = 0 V, f = 1 MHz, T_A = 25 °C		0.6		pF
	Propagation Delay Time (H → L) *3	t_{PHL}	V_{CC} = 3.3 V, R_L = 350 Ω, I_F = 7.5 mA, V_{THHL} = V_{THLH} = 1.5 V			500	ns
	Propagation Delay Time (L → H) *3	t_{PLH}				700	
	Pulse Width Distortion (PWD) *3	PWD = $\lvert t_{PHL}-t_{PLH} \rvert$				200	
	Rise Time	t_r			60		
	Fall Time	t_f			70		
	Common Mode Transient Immunity at High Level Output*4	$\lvert CM_H \rvert$	V_{CC} = 3.3 V, R_L = 350 Ω, T_A = 25 °C, I_F = 0 mA, V_O > 2 V, V_{CM} = 1 kV	15	20		kV/μs
	Common Mode Transient Immunity at Low Level Output*4	$\lvert CM_L \rvert$	V_{CC} = 3.3 V, R_L = 350 Ω, T_A = 25 °C, I_F = 7.5 mA, V_O < 0.8 V, V_{CM} = 1 kV	15	20		

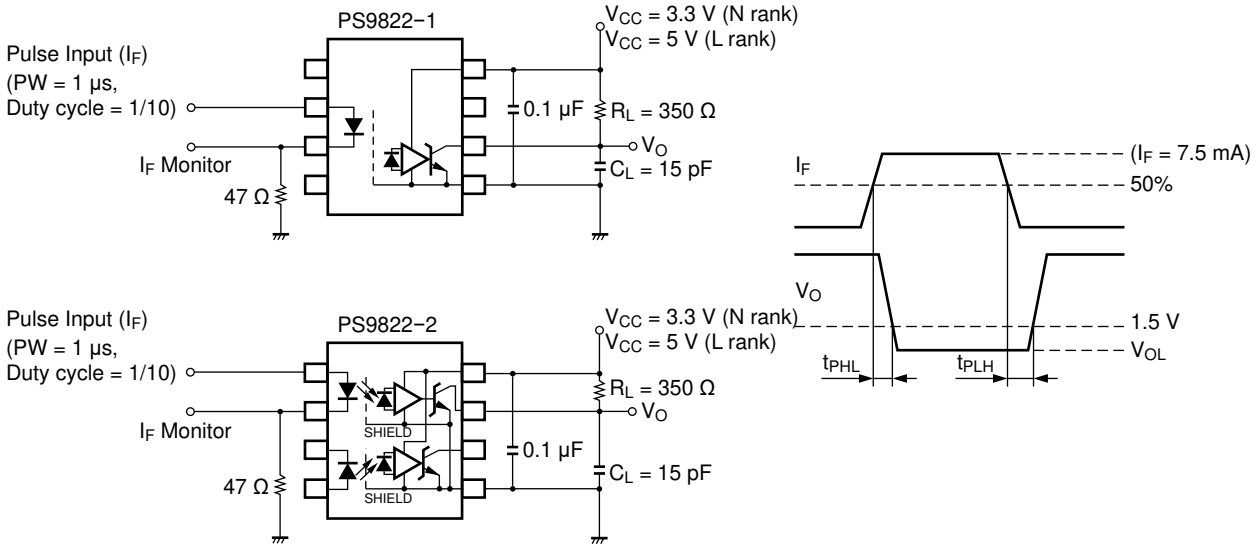
ELECTRICAL CHARACTERISTICS : L rank (TA = –40 to +100 °C, unless otherwise specified)

Parameter		Symbol	Conditions	MIN.	TYP.*5	MAX.	Unit
Diode	Forward Voltage	V_F	I_F = 10 mA, T_A = 25 °C		1.6	1.8	V
	Reverse Current	I_R	V_R = 3 V, T_A = 25 °C			10	μA
	Terminal Capacitance	C_t	V = 0 V, f = 1 MHz, T_A = 25 °C		30		pF
Detector	High Level Output Current	I_{OH}	V_{CC} = V_O = 5 V, V_F = 0.8 V		1	100	μA
	Low Level Output Voltage*6	V_{OL}	V_{CC} = 5 V, I_F = 5 mA, I_{OL} = 13 mA		0.2	0.6	V
	High Level Supply Current (PS9822-1)	I_{CCH}	V_{CC} = 5 V, I_F = 0 mA, V_O = Open			2.5	mA
	High Level Supply Current (PS9822-2)					5	
	Low Level Supply Current (PS9822-1)	I_{CCL}	V_{CC} = 5 V, I_F = 10 mA, V_O = Open			3.5	
	Low Level Supply Current (PS9822-2)					7	
Coupled	Threshold Input Current (H → L)	I_{FHL}	V_{CC} = 5 V, V_O = 0.8 V, R_L = 350 Ω		2	5	mA
	Isolation Resistance	R_{I-O}	V_{I-O} = 1 kV_{DC}, RH = 40 to 60 %, T_A = 25 °C	10^{11}			Ω
	Isolation Capacitance	C_{I-O}	V = 0 V, f = 1 MHz, T_A = 25 °C		0.6		pF
	Propagation Delay Time (H → L) *7	t_{PHL}	V_{CC} = 5 V, R_L = 350 Ω, I_F = 7.5 mA, V_{THHL} = V_{THLH} = 1.5 V			500	ns
	Propagation Delay Time (L → H) *7	t_{PLH}				700	
	Pulse Width Distortion (PWD) *7	PWD = $\lvert t_{PHL}-t_{PLH} \rvert$				200	
	Rise Time	t_r			60		
	Fall Time	t_f			70		
	Common Mode Transient Immunity at High Level Output*8	$\lvert CM_H \rvert$	V_{CC} = 5 V, R_L = 350 Ω, T_A = 25 °C, I_F = 0 mA, V_O > 2 V, V_{CM} = 1 kV	15	20		kV/μs
	Common Mode Transient Immunity at Low Level Output*8	$\lvert CM_L \rvert$	V_{CC} = 5 V, R_L = 350 Ω, T_A = 25 °C, I_F = 7.5 mA, V_O < 0.8 V, V_{CM} = 1 kV	15	20		

Notes*: 1, 5. Typical values at T_A = 25 °C

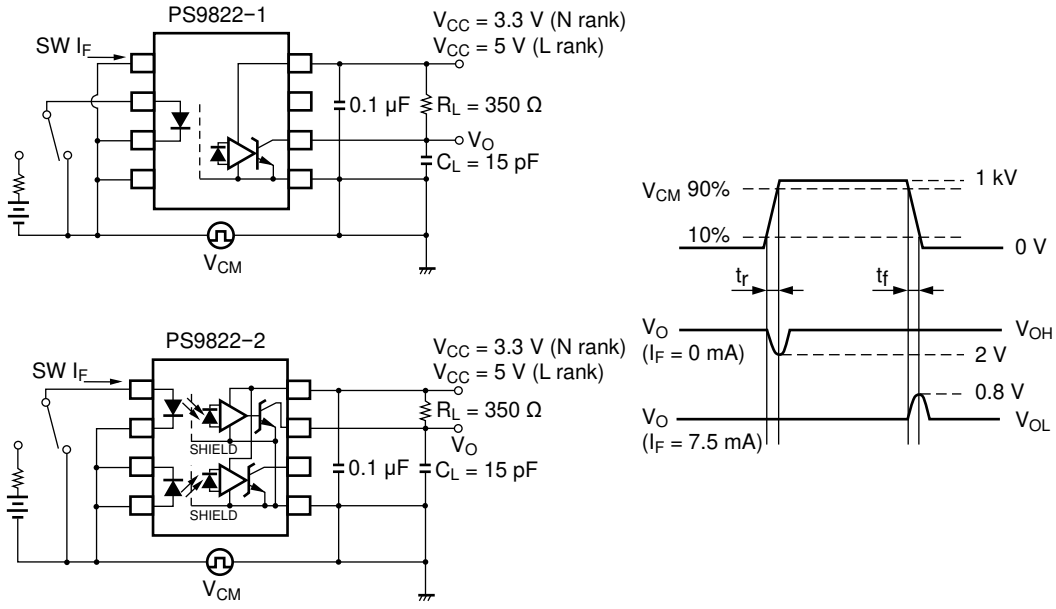
2, 6. Because V_{OL} of 2 V or more may be output when LED current input and when output supply of V_{CC} = 2.6 V or less, it is important to confirm the characteristics (operation with the power supply on and off) during design, before using this device.

3, 7. Test circuit for propagation delay time.



Remark: C_L includes probe and stray wiring capacitance.

4, 8. Test circuit for common mode transient immunity

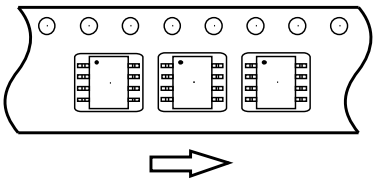


Remark: C_L includes probe and stray wiring capacitance.

TAPING SPECIFICATIONS (UNIT: mm)

Taping Direction

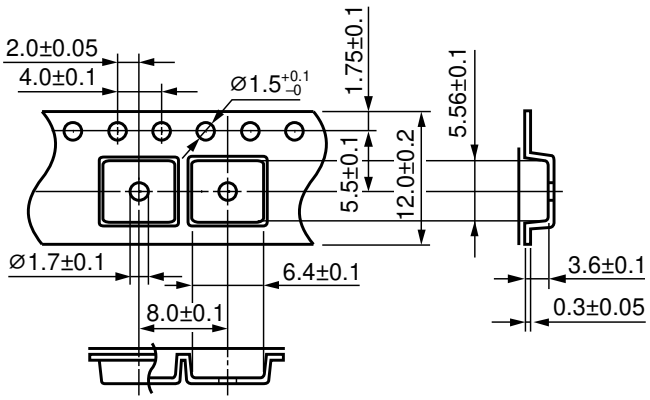
8-pin SSOP (F3)



Direction of feed

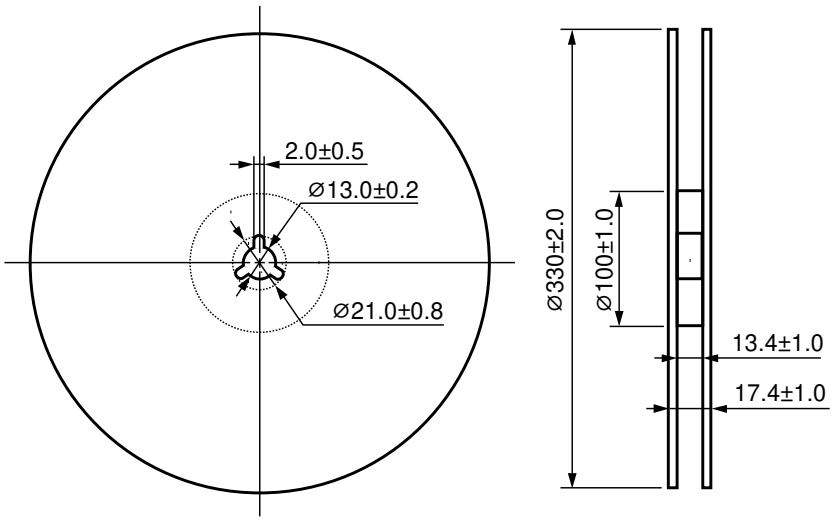
Outline and Dimensions (Tape)

(Unit : mm)



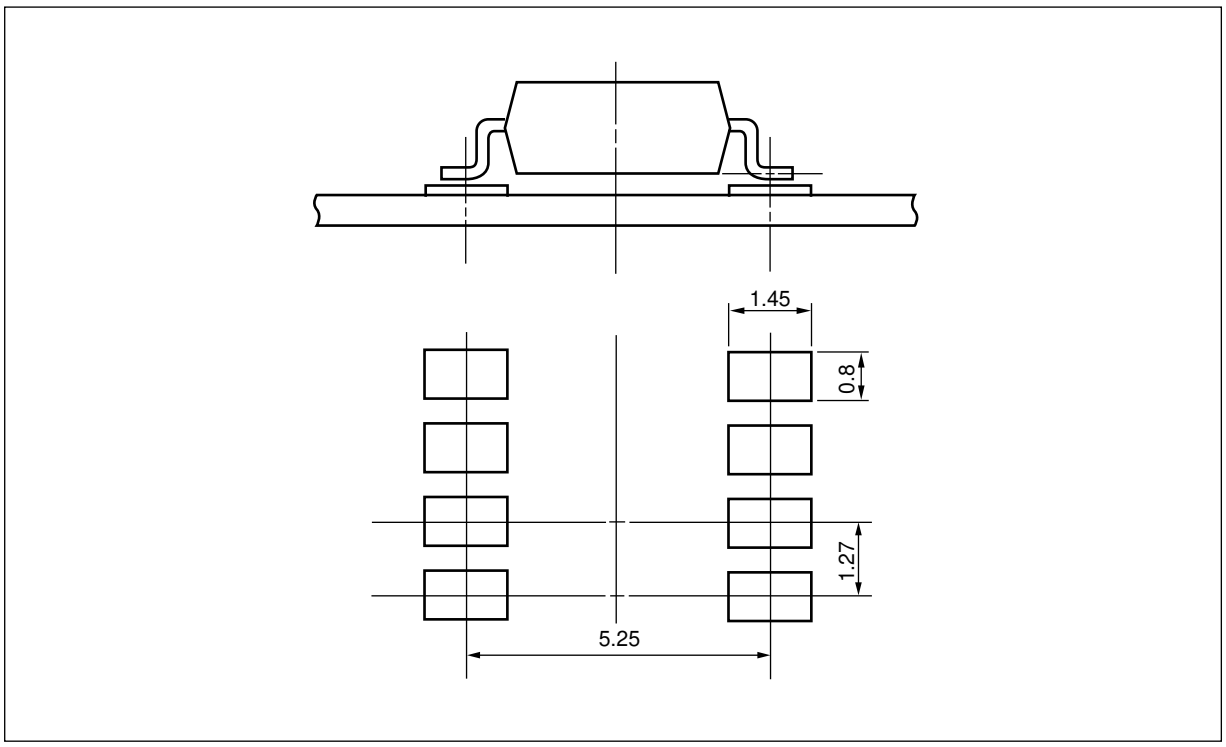
Outline and Dimensions (Reel)

(Unit : mm)



Packing: 1 500 pcs/reel

RECOMMENDED MOUNT PAD DIMENSIONS (UNIT: mm)



Remark All dimensions in this figure must be evaluated before use.

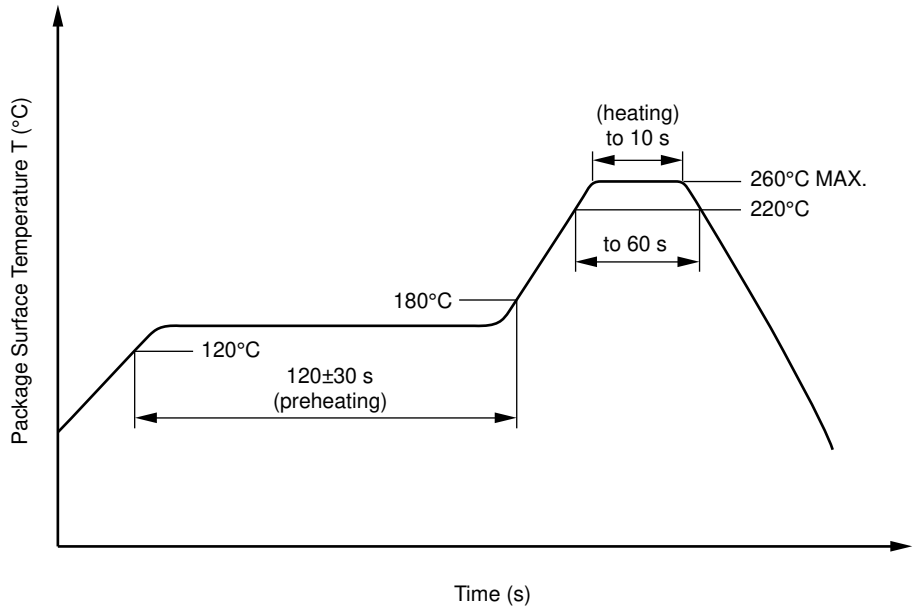
NOTES ON HANDLING

1. Recommended soldering conditions

(1) Infrared reflow soldering

• Peak reflow temperature	260 °C or below (package surface temperature)
• Time of peak reflow temperature	10 s or less
• Time of temperature higher than 220 °C	60 s or less
• Time to preheat temperature from 120 to 180 °C	120 ± 30 s
• Number of reflows	Three
• Flux	Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

Recommended Temperature Profile of Infrared Reflow



(2) Wave soldering

• Temperature	260 °C or below (molten solder temperature)
• Time	10 s or less
• Preheating conditions	120 °C or below (package surface temperature)
• Number of times	One (Allowed to be dipped in solder including plastic mold portion.)
• Flux	Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

(3) Soldering by Soldering Iron

• Peak temperature (lead part temperature)	350 °C or below
• Time (per one side)	3 s or less
• Flux	Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)
•Place	1.5 to 2.0 mm or more away from the root of the lead

(4) Cautions

• Flux cleaning	Avoid cleaning with Freon- or halogen-based (chlorinated etc.) solvents.
• Fixing/Coating	Do not use fixing agents or coatings containing halogen-based substances.

2. Cautions regarding noise

Be aware that when voltage is applied suddenly between the photocoupler's input and output or between collector-emitters at startup, the output transistor may enter the on state, even if the voltage is within the absolute maximum ratings.

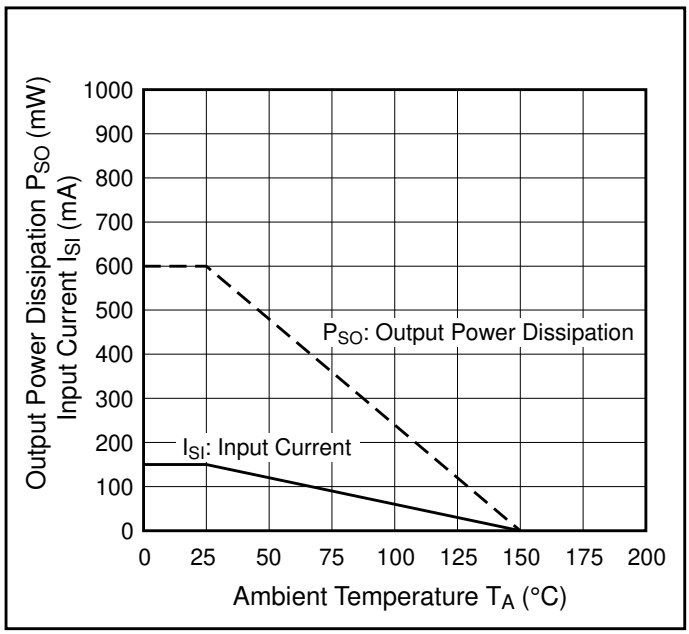
USAGE CAUTIONS

1. This product is weak for static electricity by designed with high-speed integrated circuit so protect against static electricity when handling.
2. By-pass capacitor of 0.1 μF is used between V_{CC} and GND near device. Also, ensure that the distance between the leads of the photocoupler and capacitor is no more than 10 mm.
3. Avoid storage at a high temperature and high humidity.
4. Avoid cleaning with Freon based or halogen-based (chlorinated etc.) solvents.
5. Do not use fixing agents or coatings containing halogen-based substances.

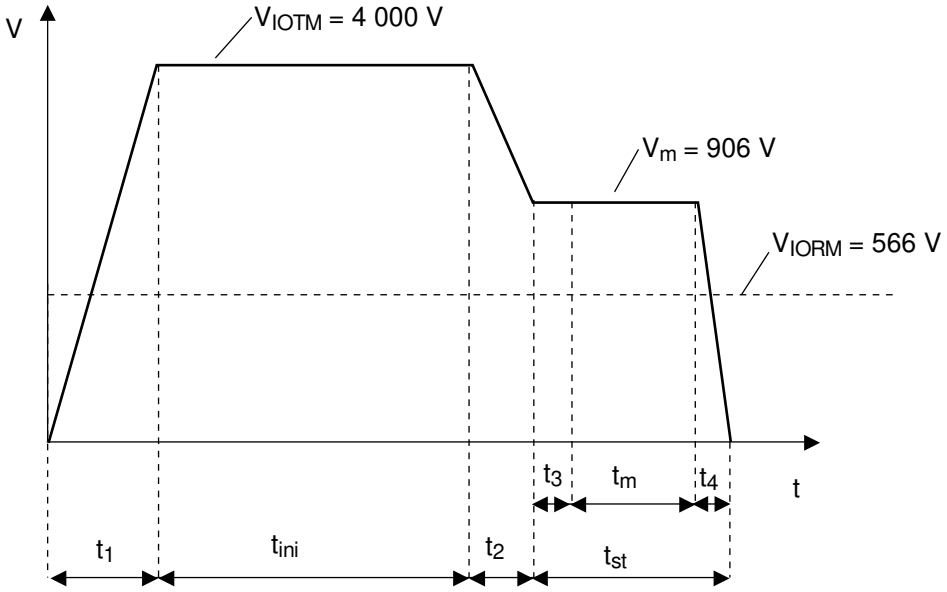
SPECIFICATION OF VDE MARKS LICENSE DOCUMENT

Parameter	Symbol	Rating	Unit
Climatic test class (IEC 60068-1/DIN EN 60068-1)		40/100/21	
Dielectric strength maximum operating isolation voltage Test voltage (partial discharge test, procedure a for type test and random test) $V_m = 1.6 \times V_{IORM.}$, $q_{pd} < 5$ pC	 V_{IORM} V_m	 566 906	 V_{peak} V_{peak}
Test voltage (partial discharge test, procedure b for all devices) $V_m = 1.875 \times V_{IORM.}$, $q_{pd} < 5$ pC	V_m	1 062	V_{peak}
Highest permissible overvoltage	V_{IOTM}	4 000	V_{peak}
Degree of pollution (IEC 60664-1/DIN EN 60664-1 (VDE 0110-1))		2	
Comparative tracking index (IEC 60112/DIN EN 60112 (VDE 0303-11))	CTI	175	
Material group (IEC 60664-1/DIN EN 60664-1 (VDE 0110-1))		III a	
Storage temperature range	T_{stg}	−55 to +125	°C
Operating temperature range	T_A	−40 to +100	°C
Isolation resistance, minimum value V_{I-O} = 500 V dc, T_A = 25 °C V_{I-O} = 500 V dc, T_A = maximum temperature of rating, at least 100 °C	 R_{I-O} MIN. R_{I-O} MIN.	 10^{12} 10^{11}	 Ω Ω
Safety maximum ratings (maximum permissible in case of fault, see thermal derating curve) Maximum ambient temperature Maximum input current Maximum output power dissipation Isolation resistance, minimum value at V_{I-O} = 500 V dc, $T_A = T_S$	 T_S I_{SI} P_{SO} R_{I-O} MIN.	 150 150 600 10^9	 °C mA mW Ω

Dependence of maximum safety ratings on ambient temperature

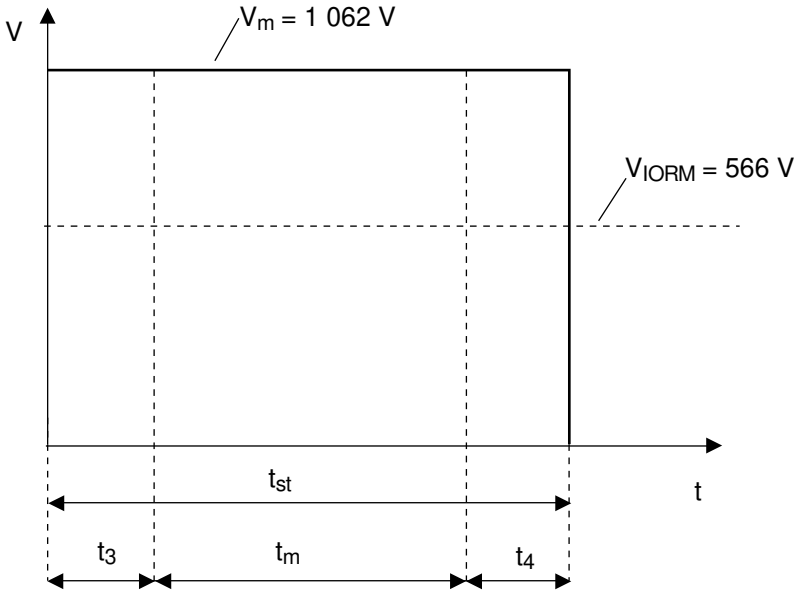


Method a) Destructive Test, Type and Sample Test



t_1, t_2 = 1 to 10 sec
t_3, t_4 = 1 sec
t_m = 10 sec
t_{st} = 12 sec
t_{ini} = 60 sec

Method b) Non-destructive Test, 100% Production Test



t_3, t_4 = 0.1 sec
t_m = 1.0 sec
t_{st} = 1.2 sec

Caution GaAs Products	This product uses gallium arsenide (GaAs). GaAs vapor and powder are hazardous to human health if inhaled or ingested, so please observe the following points. • Follow related laws and ordinances when disposing of the product. If there are no applicable laws and/or ordinances, dispose of the product as recommended below. 1. Commission a disposal company able to (with a license to) collect, transport and dispose of materials that contain arsenic and other such industrial waste materials. 2. Exclude the product from general industrial waste and household garbage, and ensure that the product is controlled (as industrial waste subject to special control) up until final disposal. • Do not burn, destroy, cut, crush, or chemically dissolve the product. • Do not lick the product or i any way allow it to enter the mouth.

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